



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DB2X20600L

Silicon epitaxial planar type

For high frequency rectification
 DB3X206K in Mini2 type package

■ Features

- Low forward voltage VF
- Small reverse leakage current
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: D3

■ Packaging

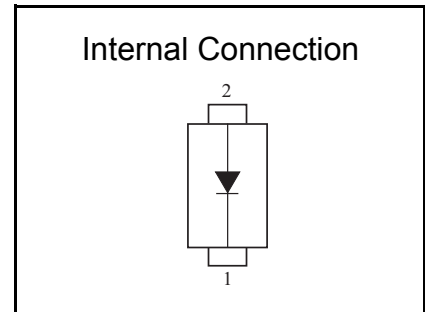
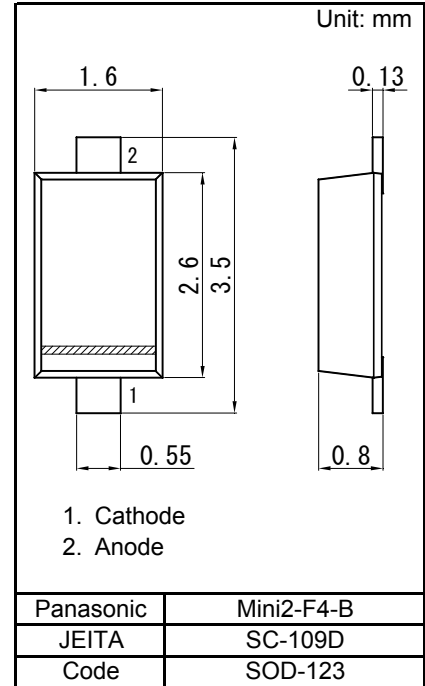
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	20	V
Repetitive peak reverse voltage	VRRM	20	V
Forward current (Average) *1	IF(AV)	1	A
Non-repetitive peak forward surge current *2	IFSM	3	A
Junction temperature	Tj	125	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +125	°C

Note: *1 For embedded alumina substrate

*2 50 Hz sine wave 1 cycle (Non-repetitive peak current)

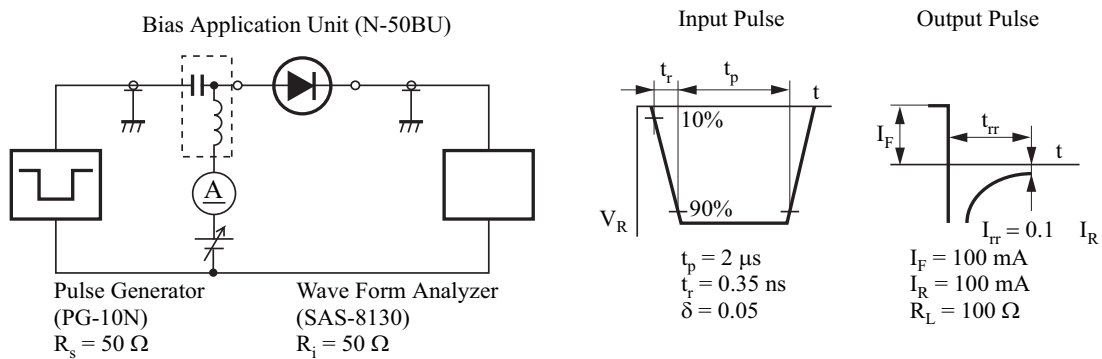




■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

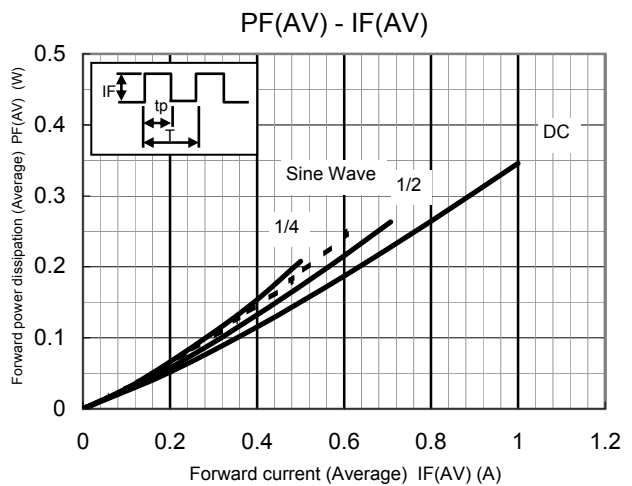
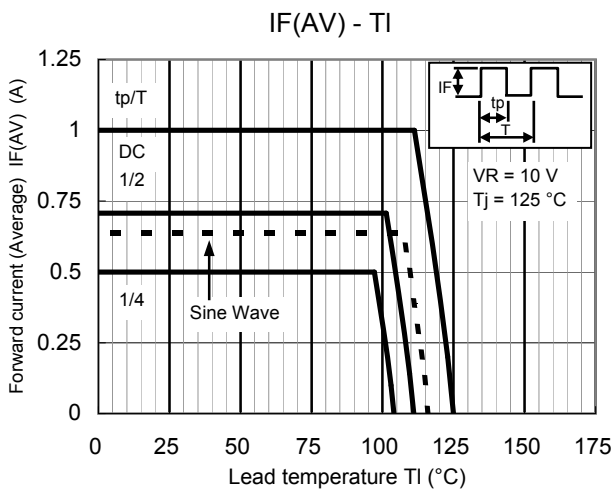
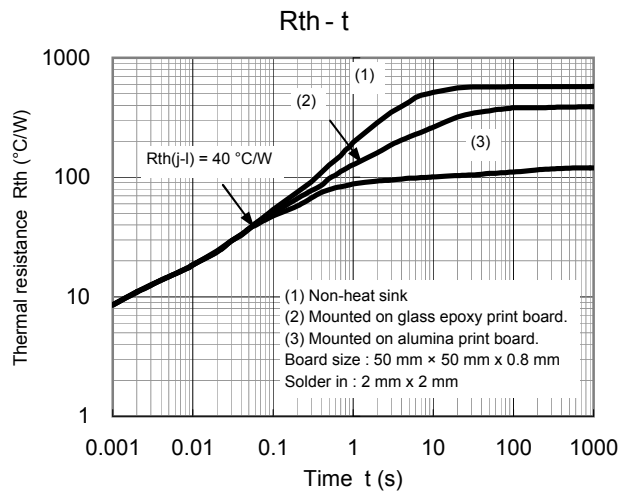
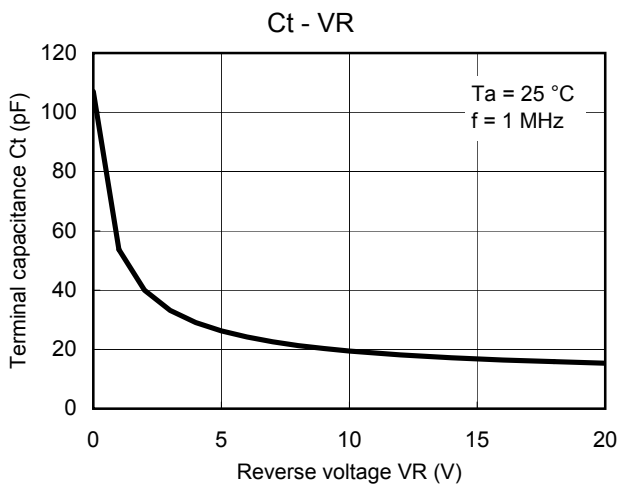
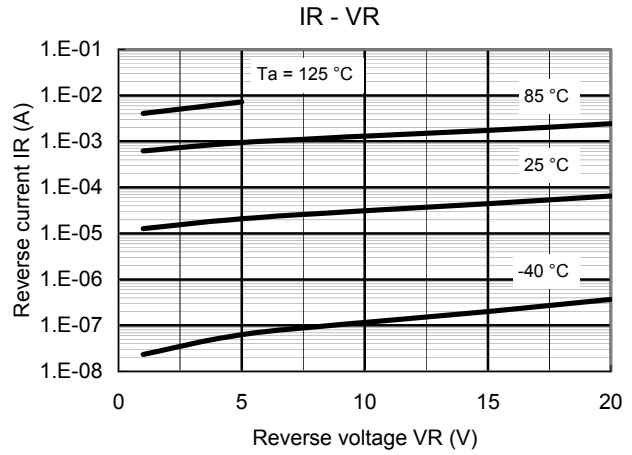
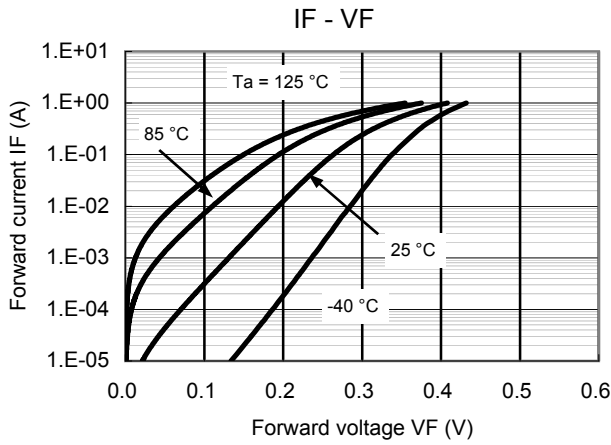
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 1.0 A			0.45	V
Reverse current	IR	VR = 20 V			100	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		20		pF
Reverse recovery time *1	trr	IF = IR = 100 mA, Irr = 0.1 × IR, RL = 100 Ω		6		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 3. *1 trr test circuit





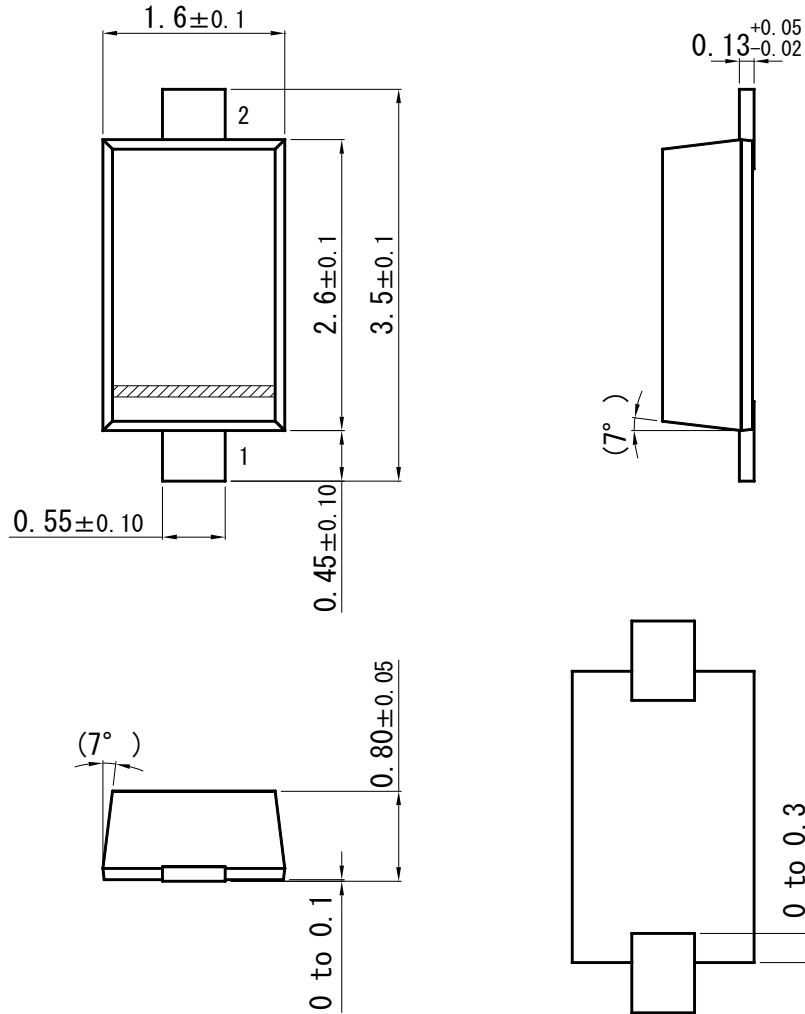
Technical Data (reference)



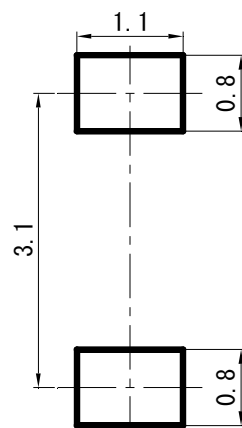


Mini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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